# PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Sameer Vermani	01/29/2013
Richard Van Nee	01/29/2013
Albert Van Zelst	01/29/2013
Vincent Knowles Jones	01/28/2013
Hemanth Sampath	02/18/2013

#### **RECEIVING PARTY DATA**

Name:	Qualcomm Incorporated		
Street Address:	et Address: 5775 Morehouse Drive		
City:	San Diego		
State/Country:	CALIFORNIA		
Postal Code:	92121		

# PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13734101

## **CORRESPONDENCE DATA**

**Fax Number**: 8586582502

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 858-658-4351

Email: us-docketing@qualcomm.com

Correspondent Name: QUALCOMM INCORPORATED

Address Line 1: 5775 MOREHOUSE DR.

Address Line 4: SAN DIEGO, CALIFORNIA 92121

Address Line 4: SAN DIEGO, CALIFORNIA 92121

Signature:	/Shae Penturf/	
NAME OF SUBMITTER:	Shae Penturf	
ATTORNEY DOCKET NUMBER:	122139	

502296201 REEL: 030136 FRAME: 0932

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Date:	04/02/2013
Total Attachments: 12 source=122139_Signed_Assignments_2013	3-2-21#page2.tif 3-2-21#page3.tif 3-2-21#page4.tif 3-2-21#page5.tif 3-2-21#page6.tif 3-2-21#page7.tif 3-2-21#page8.tif 3-2-21#page8.tif 3-2-21#page8.tif 3-2-21#page9.tif 3-2-21#page9.tif

# WHEREAS, WE,

- 1. Sameer Vermani, a citizen of India, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
- 2. Richard van Nee, a citizen of The Netherlands, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
- 3. Albert van Zelst, a citizen of The Netherlands, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,
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- 5. Hemanth Sampath, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive San Diego, CA 92121 and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SYSTEMS AND METHODS OF USING SPACE TIME BLOCK CODES** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/734,101 filed January 4, 2013, Qualcomm Reference No. 122139, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). 61/625,045, filed April 16, 2012, Qualcomm Reference No. 122139P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

QUALCOMM Ref. No. 122139

Page 3 of 3

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	SAN DIEGO	on 01/29/2013	Sameer Vermani
	LOCATION	DATE	Sameer Vermani
Done at	LOCATION ,	on	Disk and an all
	200111011	DATE	Richard van Nee
Done at	LOCATION,	on	Albert van Zelst
	LOCATION	DATE	Albert van Zelst
Done at _		on	
	LOCATION	DATE	Vincent Knowles Jones
Done at		On	
	LOCATION	on	Hemanth Sampath

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have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to SYSTEMS AND METHODS OF USING SPACE TIME BLOCK CODES (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

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AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	, on		
	LOCATION	DATE	Sameer Vermani
Done at	Breuhelen, on LOCATION	7 24 24 2013 O DATE	Richard van Nee
Done at	<u>SLEUUELEN</u> , on LOCATION	<u>J4W 24, 2013</u> DATE	Albert van Zelst
Done at	LOCATION , on	DATE	Vincent Knowles Jones
Done at	, on	DATE	Hemanth Samnath

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Done at		on	
	LOCATION	DATE	Sameer Vermani
Done at	,(	DATE	
	LOCATION	DATE	Richard van Nee
Done at _	,	on	
	an Jose CA, o		Albert van Zelst  Vincen Knowles Jones
Done at _	LOCATION , 0	n	Hemanth Samnath
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## **PATENT**

QUALCOMM Ref. No. 122139

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Done at		, on		
	LOCATION		DATE	Sameer Vermani
Done at_		, on	DATE	
	LOCATION		DATE	Richard van Nee
Done at _		, on	DATE	
	LOCATION		DATE	Albert van Zelst
Done at _		, on _	DATE:	
	LOCATION		DATE	Vincent Knowles Jones
g.e.			8	an K
Done at $\frac{\Delta}{2}$	LOCATION	_, on _	02/18/13	Merole
	LOCATION		DATE	Hemanth Samnath

PATENT REEL: 030136 FRAME: 0945

**RECORDED: 04/02/2013**